

WAFER PRODUCTION METHOD AND WAFER PRODUCTION MACHINE

ABSTRACT

A wafer production method includes a separating layer forming step of forming, in the ingot, a separating layer that includes modified portions and cracks, by relatively moving the ingot and a focal point of a laser beam of a wavelength having transmissivity for the ingot, with the focal point positioned at a depth corresponding to a thickness of the wafer, a wafer separating step of separating the wafer from the ingot by using the separating layer as a separation starting interface, a tape bonding step of bonding an adhesive tape to at least one of a separated surface of the wafer and a resulting fresh end surface of the ingot, a tape separating step of removing separation debris stuck on the at least one surface, by separating the adhesive tape from the at least one surface, and a grinding step of grinding the at least one surface from which the separation debris has been removed. A wafer production machine is also disclosed.

[FIG. 3]